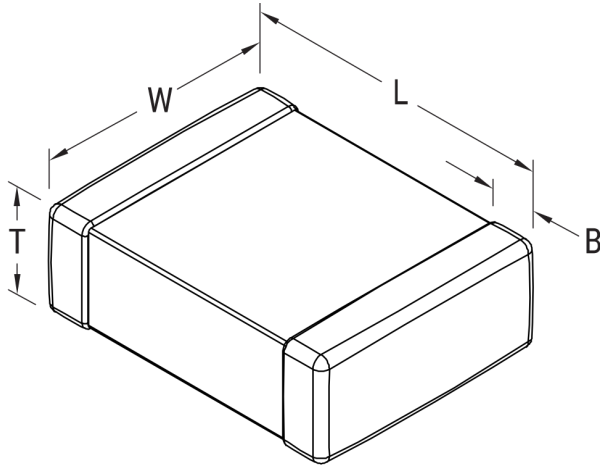




Click [here](#) for the 3D model.

Dimensions

Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
T	0.3mm +/-0.03mm
B	0.15mm +/-0.05mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	15000

General Information

Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	0.3 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.3 pF
Capacitance Tolerance	+/-0.1 pF
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.2% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	406